



Initial Product/Process Change Notification

Document #: IPCN24802X

Issue Date: 29 Sep 2022

Title of Change:	Qualification of Minigates Vanguard die in SC88 and SC88A Package.			
Proposed First Ship date:	31 Mar 2023 or earlier if approved by customer			
Contact Information:	Contact your local onsemi Sales Office or logic.fpcn@onsemi.com			
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.			
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >			
Marking of Parts/ Traceability of Change:	Custom source on label will show TW instead of JP (TPSCo) to indicate new die source from Vanguard.			
Change Category:	Assembly Change, Wafer Fab Change			
Change Sub-Category(s):	Manufacturing Process Change, Manufacturing Site Addition			
Sites Affected:				
onsemi Sites			External Foundry/Subcon Sites	
onsemi Leshan, China			Vanguard International Semiconductor, Taiwan	
onsemi Seremban, Malaysia				
Description and Purpose:				
This Initial Notification announces that onsemi is qualifying Vanguard wafer fabrication for SC88 and SC88A package.				
SC88 and SC88A package:				
	From		To	
Assembly Site	onsemi Seremban	Leshan Phoenix Semiconductor	onsemi Seremban	Leshan Phoenix Semiconductor
Die Source	TPSCo	TPSCo	TPSCO or Vanguard	TPSCO or Vanguard
<p><i>*Only those approved OPNs under FPCN23285X are running at both sites (SBN and Leshan), else Leshan is the only site for before. Those * in the qualification vehicle column are the OPNs running at both sites.</i></p> <p>There is no product marking change as a result of this change.</p>				



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Qualification Plan:

QV DEVICE NAME: NL27WZ14DFT2G

RMS: L85492 / L82712

PACKAGE: SC88

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
ELFR	JESD22-A108	Ta=125°C, 100 % max rated Vcc	48 hrs
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
PC+TC	JESD22-A104	Ta= -65°C to + 150°C	500 cyc
PC+HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias Vcc	96 hrs
PC+uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 / JESD-A113	MSL 1 @260 °C	-
RSH	JESD22- B106	Ta = 265C, 10 sec	-

QV DEVICE NAME: MC74VHC1G14DFT1G

RMS: S85493

PACKAGE: SC88A

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
PC+TC	JESD22-A104	Ta= -65°C to + 150°C	500 cyc
PC+HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias Vcc	96 hrs
PC+uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 / JESD-A113	MSL 1 @260 °C	-
RSH	JESD22- B106	Ta = 265C, 10 sec	-

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

To view attached Parts List:

1. Download pdf copy of the PCN to your computer
2. Open the downloaded pdf copy of the PCN
3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
4. Then click on the attached file/s